

Bid Bulletin No. 4

Consulting Service for the Updating of the Semiconductor and Electronics Industry Roadmap, and the Conduct of Feasibility Study on Establishing a Wafer Fabrication Plant Bidding No. 24-010

June 11, 2024

This Bid Bulletin No. 4 is hereby issued to modify or amend the Bidding Documents.

Schedule of Proceedings

Activity	Schedule
Pre-Bid Conference	24 June 2024, 9:30 AM, for the Pre-Bid Conference through video conference with the following details: Zoom Meeting: https://zoom.us/j/99561340538?pwd=urAsa4nQOu3BvCqGecY6QfvktHrXAQ.1 Meeting ID: 995 6134 0538 Passcode: BAC2024
Submission of Technical and Financial Documents and Opening of Technical Documents	08 July 2024, 9:00 AM, for the Submission of Technical and Financial Documents, and 9:30 AM for the Opening of Technical Documents through video conference with the following details: Zoom Meeting: https://zoom.us/j/95645456781?pwd=mCcT6lfNnUbxJgwR1SwBLgcUipR3nc.1 Meeting ID: 956 4545 6781 Passcode: BAC2024
Opening of Financial Documents	15 July 2024, 9:30 AM, for the Opening of Financial Documents through zoom video conference with the following details:

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11 June 2024

Zoom Meeting: https://zoom.us/j/96625032685?pwd=u3eY3nLq0DFZ4 EgMejLV31GYBYEDO7.1
Meeting ID: 966 2503 2685 Passcode: BAC2024

For the guidance and information of all concerned.

SGD.

KRISTIAN R. ABLAN

Assistant Secretary

Chairperson, DTI Bids and Awards Committee

Conforme:	
Name and Signature of Authorized Representative Date:	